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Applicants: A. Soutar and F. McGrath
Attorney Docket No. 23905-029

Please replace the paragraph beginning at page 20, line 10, with the following rewritten paragraph:

B⁶ -- The plating composition used in this aspect of the invention may be an immersion plating composition based on any plating composition used in the PCB industry. --

SB Please replace the paragraph beginning at page 24, line 5, with the following rewritten paragraph:

B⁷ -- This invention has been found to provide considerable advantages in preventing tarnishing and conferring humidity resistance on the bare boards produced so that additional protection is provided between the bare board manufacture stage and the component-attachment stage. Solderability is found to be enhanced. --